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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	600
Number of Logic Elements/Cells	2700
Total RAM Bits	81920
Number of I/O	94
Number of Gates	128236
Voltage - Supply	1.71V ~ 1.89V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	144-TFBGA, CSPBGA
Supplier Device Package	144-LCSBGA (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xcv100e-6cs144c

Table 1: **Virtex-E Field-Programmable Gate Array Family Members**

Device	System Gates	Logic Gates	CLB Array	Logic Cells	Differential I/O Pairs	User I/O	BlockRAM Bits	Distributed RAM Bits
XCV50E	71,693	20,736	16 x 24	1,728	83	176	65,536	24,576
XCV100E	128,236	32,400	20 x 30	2,700	83	196	81,920	38,400
XCV200E	306,393	63,504	28 x 42	5,292	119	284	114,688	75,264
XCV300E	411,955	82,944	32 x 48	6,912	137	316	131,072	98,304
XCV400E	569,952	129,600	40 x 60	10,800	183	404	163,840	153,600
XCV600E	985,882	186,624	48 x 72	15,552	247	512	294,912	221,184
XCV1000E	1,569,178	331,776	64 x 96	27,648	281	660	393,216	393,216
XCV1600E	2,188,742	419,904	72 x 108	34,992	344	724	589,824	497,664
XCV2000E	2,541,952	518,400	80 x 120	43,200	344	804	655,360	614,400
XCV2600E	3,263,755	685,584	92 x 138	57,132	344	804	753,664	812,544
XCV3200E	4,074,387	876,096	104 x 156	73,008	344	804	851,968	1,038,336

Virtex-E Compared to Virtex Devices

The Virtex-E family offers up to 43,200 logic cells in devices up to 30% faster than the Virtex family.

I/O performance is increased to 622 Mb/s using Source Synchronous data transmission architectures and synchronous system performance up to 240 MHz using singled-ended SelectI/O technology. Additional I/O standards are supported, notably LVPECL, LVDS, and BLVDS, which use two pins per signal. Almost all signal pins can be used for these new standards.

Virtex-E devices have up to 640 Kb of faster (250 MHz) block SelectRAM, but the individual RAMs are the same size and structure as in the Virtex family. They also have eight DLLs instead of the four in Virtex devices. Each individual DLL is slightly improved with easier clock mirroring and 4x frequency multiplication.

V_{CCINT}, the supply voltage for the internal logic and memory, is 1.8 V, instead of 2.5 V for Virtex devices. Advanced processing and 0.18 µm design rules have resulted in smaller dice, faster speed, and lower power consumption.

I/O pins are 3 V tolerant, and can be 5 V tolerant with an external 100 Ω resistor. PCI 5 V is not supported. With the addition of appropriate external resistors, any pin can tolerate any voltage desired.

Banking rules are different. With Virtex devices, all input buffers are powered by V_{CCINT}. With Virtex-E devices, the LVTTL, LVCMOS2, and PCI input buffers are powered by the I/O supply voltage V_{CCO}.

The Virtex-E family is not bitstream-compatible with the Virtex family, but Virtex designs can be compiled into equivalent Virtex-E devices.

The same device in the same package for the Virtex-E and Virtex families are pin-compatible with some minor exceptions. See the data sheet pinout section for details.

General Description

The Virtex-E FPGA family delivers high-performance, high-capacity programmable logic solutions. Dramatic increases in silicon efficiency result from optimizing the new architecture for place-and-route efficiency and exploiting an aggressive 6-layer metal 0.18 µm CMOS process. These advances make Virtex-E FPGAs powerful and flexible alternatives to mask-programmed gate arrays. The Virtex-E family includes the nine members in Table 1.

Building on experience gained from Virtex FPGAs, the Virtex-E family is an evolutionary step forward in programmable logic design. Combining a wide variety of programmable system features, a rich hierarchy of fast, flexible interconnect resources, and advanced process technology, the Virtex-E family delivers a high-speed and high-capacity programmable logic solution that enhances design flexibility while reducing time-to-market.

Virtex-E Architecture

Virtex-E devices feature a flexible, regular architecture that comprises an array of configurable logic blocks (CLBs) surrounded by programmable input/output blocks (IOBs), all interconnected by a rich hierarchy of fast, versatile routing

Initialization in Verilog and Synopsys

The block SelectRAM+ structures can be initialized in Verilog for both simulation and synthesis for inclusion in the EDIF output file. The simulation of the Verilog code uses a defparam to pass the initialization. The Synopsys FPGA compiler does not presently support defparam. The initialization values instead attach as attributes to the RAM by a built-in Synopsys dc_script. The translate_off statement stops synthesis translation of the defparam statements. The following code illustrates a module that employs these techniques.

Design Examples

Creating a 32-bit Single-Port RAM

The true dual-read/write port functionality of the block SelectRAM+ memory allows a single port, 128 deep by 32-bit wide RAM to be created using a single block SelectRAM+ cell as shown in Figure 35.

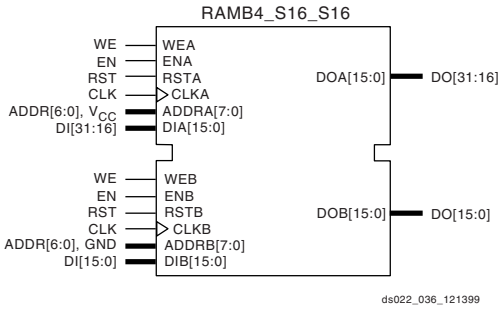

Figure 35: **Single Port 128 x 32 RAM**

Interleaving the memory space, setting the LSB of the address bus of Port A to 1 (V_{CC}), and the LSB of the address bus of Port B to 0 (GND), allows a 32-bit wide single port RAM to be created.

Creating Two Single-Port RAMs

The true dual-read/write port functionality of the block SelectRAM+ memory allows a single RAM to be split into two single port memories of 2K bits each as shown in Figure 36.

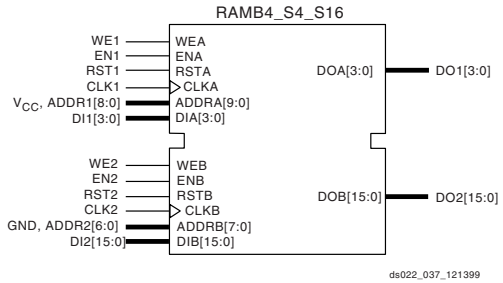

Figure 36: **512 x 4 RAM and 128 x 16 RAM**

In this example, a 512K x 4 RAM (Port A) and a 128 x 16 RAM (Port B) are created out of a single block SelectRAM+. The address space for the RAM is split by fixing the MSB of Port A to 1 (V_{CC}) for the upper 2K bits and the MSB of Port B to 0 (GND) for the lower 2K bits.

Block Memory Generation

The CoreGen program generates memory structures using the block SelectRAM+ features. This program outputs VHDL or Verilog simulation code templates and an EDIF file for inclusion in a design.

Fundamentals

Modern bus applications, pioneered by the largest and most influential companies in the digital electronics industry, are commonly introduced with a new I/O standard tailored specifically to the needs of that application. The bus I/O standards provide specifications to other vendors who create products designed to interface with these applications. Each standard often has its own specifications for current, voltage, I/O buffering, and termination techniques.

The ability to provide the flexibility and time-to-market advantages of programmable logic is increasingly dependent on the capability of the programmable logic device to support an ever increasing variety of I/O standards

The SelectI/O resources feature highly configurable input and output buffers which provide support for a wide variety of I/O standards. As shown in Table 18, each buffer type can support a variety of voltage requirements.

Table 18: **Virtex-E Supported I/O Standards**

I/O Standard	Output V_{CCO}	Input V_{CCO}	Input V_{REF}	Board Termination Voltage (V_{TT})
LVTTL	3.3	3.3	N/A	N/A
LVCMOS2	2.5	2.5	N/A	N/A
LVCMOS18	1.8	1.8	N/A	N/A
SSTL3 I & II	3.3	N/A	1.50	1.50
SSTL2 I & II	2.5	N/A	1.25	1.25
GTL	N/A	N/A	0.80	1.20
GTL+	N/A	N/A	1.0	1.50
HSTL I	1.5	N/A	0.75	0.75
HSTL III & IV	1.5	N/A	0.90	1.50
CTT	3.3	N/A	1.50	1.50
AGP-2X	3.3	N/A	1.32	N/A
PCI33_3	3.3	3.3	N/A	N/A
PCI66_3	3.3	3.3	N/A	N/A
BLVDS & LVDS	2.5	N/A	N/A	N/A
LVPECL	3.3	N/A	N/A	N/A

Overview of Supported I/O Standards

This section provides a brief overview of the I/O standards supported by all Virtex-E devices.

While most I/O standards specify a range of allowed voltages, this document records typical voltage values only. Detailed information on each specification can be found on the Electronic Industry Alliance Jedec website at:

http://www.jedec.org

LVTTL — Low-Voltage TTL

The Low-Voltage TTL, or LVTTL standard is a general purpose EIA/JESDSA standard for 3.3V applications that uses an LVTTL input buffer and a Push-Pull output buffer. This standard requires a 3.3V output source voltage (V_{CCO}), but does not require the use of a reference voltage (V_{REF}) or a termination voltage (V_{TT}).

LVCMOS2 — Low-Voltage CMOS for 2.5 Volts

The Low-Voltage CMOS for 2.5 Volts or lower, or LVCMOS2 standard is an extension of the LVCMOS standard (JESD 8.-5) used for general purpose 2.5V applications. This standard requires a 2.5V output source voltage (V_{CCO}), but does not require the use of a reference voltage (V_{REF}) or a board termination voltage (V_{TT}).

LVCMOS18 — 1.8 V Low Voltage CMOS

This standard is an extension of the LVCMOS standard. It is used in general purpose 1.8 V applications. The use of a reference voltage (V_{REF}) or a board termination voltage (V_{TT}) is not required.

PCI — Peripheral Component Interface

The Peripheral Component Interface, or PCI standard specifies support for both 33 MHz and 66 MHz PCI bus applications. It uses a LVTTL input buffer and a Push-Pull output buffer. This standard does not require the use of a reference voltage (V_{REF}) or a board termination voltage (V_{TT}), however, it does require a 3.3V output source voltage (V_{CCO}).

GTL — Gunning Transceiver Logic Terminated

The Gunning Transceiver Logic, or GTL standard is a high-speed bus standard (JESD8.3) invented by Xerox. Xilinx has implemented the terminated variation for this standard. This standard requires a differential amplifier input buffer and a Open Drain output buffer.

GTL+ — Gunning Transceiver Logic Plus

The Gunning Transceiver Logic Plus, or GTL+ standard is a high-speed bus standard (JESD8.3) first used by the Pentium Pro processor.

HSTL — High-Speed Transceiver Logic

The High-Speed Transceiver Logic, or HSTL standard is a general purpose high-speed, 1.5V bus standard sponsored by IBM (EIA/JESD 8-6). This standard has four variations or classes. SelectI/O devices support Class I, III, and IV. This

Table 44: **Bidirectional I/O Library Macros**

Name	Inputs	Bidirectional	Outputs
IOBUFDS_FD_LVDS	D, T, C	IO, IOB	Q
IOBUFDS_FDE_LVDS	D, T, CE, C	IO, IOB	Q
IOBUFDS_FDC_LVDS	D, T, C, CLR	IO, IOB	Q
IOBUFDS_FDCE_LVDS	D, T, CE, C, CLR	IO, IOB	Q
IOBUFDS_FDP_LVDS	D, T, C, PRE	IO, IOB	Q
IOBUFDS_FDPE_LVDS	D, T, CE, C, PRE	IO, IOB	Q
IOBUFDS_FDR_LVDS	D, T, C, R	IO, IOB	Q
IOBUFDS_FDRE_LVDS	D, T, CE, C, R	IO, IOB	Q
IOBUFDS_FDS_LVDS	D, T, C, S	IO, IOB	Q
IOBUFDS_FDSE_LVDS	D, T, CE, C, S	IO, IOB	Q
IOBUFDS_LD_LVDS	D, T, G	IO, IOB	Q
IOBUFDS_LDE_LVDS	D, T, GE, G	IO, IOB	Q
IOBUFDS_LDC_LVDS	D, T, G, CLR	IO, IOB	Q
IOBUFDS_LDCE_LVDS	D, T, GE, G, CLR	IO, IOB	Q
IOBUFDS_LDP_LVDS	D, T, G, PRE	IO, IOB	Q
IOBUFDS_LDPE_LVDS	D, T, GE, G, PRE	IO, IOB	Q

Revision History

The following table shows the revision history for this document.

Date	Version	Revision
12/7/99	1.0	Initial Xilinx release.
1/10/00	1.1	Re-released with spd.txt v. 1.18, FG860/900/1156 package information, and additional DLL, Select RAM and SelectI/O information.
1/28/00	1.2	Added Delay Measurement Methodology table, updated SelectI/O section, Figures 30, 54, & 55, text explaining Table 5, T_{BYP} values, buffered Hex Line info, p. 8, I/O Timing Measurement notes, notes for Tables 15, 16, and corrected F1156 pinout table footnote references.
2/29/00	1.3	Updated pinout tables, V_{CC} page 20, and corrected Figure 20.
5/23/00	1.4	Correction to table on p. 22.
7/10/00	1.5	• Numerous minor edits. • Data sheet upgraded to Preliminary. • Preview -8 numbers added to **Virtex-E Electrical Characteristics** tables.
8/1/00	1.6	• Reformatted entire document to follow new style guidelines. • Changed speed grade values in tables on pages 35-37.

CLB Arithmetic Switching Characteristics

Setup times not listed explicitly can be approximated by decreasing the combinatorial delays by the setup time adjustment listed. Precise values are provided by the timing analyzer.

Description	Symbol	Speed Grade(1)				Units
		Min	-8	-7	-6	
Combinatorial Delays						
F operand inputs to X via XOR	T_{OPX}	0.32	0.68	0.8	0.8	ns, max
F operand input to XB output	T_{OPXB}	0.35	0.65	0.8	0.9	ns, max
F operand input to Y via XOR	T_{OPY}	0.59	1.07	1.4	1.5	ns, max
F operand input to YB output	T_{OPYB}	0.48	0.89	1.1	1.3	ns, max
F operand input to COUT output	T_{OPCYF}	0.37	0.71	0.9	1.0	ns, max
G operand inputs to Y via XOR	T_{OPGY}	0.34	0.72	0.8	0.9	ns, max
G operand input to YB output	T_{OPGYB}	0.47	0.78	1.2	1.3	ns, max
G operand input to COUT output	T_{OPCYG}	0.36	0.60	0.9	1.0	ns, max
BX initialization input to COUT	T_{BXCY}	0.19	0.36	0.51	0.57	ns, max
CIN input to X output via XOR	T_{CINX}	0.27	0.50	0.6	0.7	ns, max
CIN input to XB	T_{CINXB}	0.02	0.04	0.07	0.08	ns, max
CIN input to Y via XOR	T_{CINY}	0.26	0.45	0.7	0.7	ns, max
CIN input to YB	T_{CINYB}	0.16	0.28	0.38	0.43	ns, max
CIN input to COUT output	T_{BYP}	0.05	0.10	0.14	0.15	ns, max
Multiplier Operation						
F1/2 operand inputs to XB output via AND	T_{FANDXB}	0.10	0.30	0.35	0.39	ns, max
F1/2 operand inputs to YB output via AND	T_{FANDYB}	0.28	0.56	0.7	0.8	ns, max
F1/2 operand inputs to COUT output via AND	T_{FANDCY}	0.17	0.38	0.46	0.51	ns, max
G1/2 operand inputs to YB output via AND	T_{GANDYB}	0.20	0.46	0.55	0.7	ns, max
G1/2 operand inputs to COUT output via AND	T_{GANDCY}	0.09	0.28	0.30	0.34	ns, max
Setup and Hold Times before/after Clock CLK						
CIN input to FFX	T_{CCKX}/T_{CKCX}	0.47 / 0	1.0 / 0	1.2 / 0	1.3 / 0	ns, min
CIN input to FFY	T_{CCKY}/T_{CKCY}	0.49 / 0	0.92 / 0	1.2 / 0	1.3 / 0	ns, min

Notes:

1. A Zero “0” Hold Time listing indicates no hold time or a negative hold time. Negative values can not be guaranteed “best-case”, but if a “0” is listed, there is no positive hold time.

Global Clock Set-Up and Hold for LVTTL Standard, *without* DLL

Description[1]	Symbol	Device	Speed Grade[2, 3]				Units
			Min	-8	-7	-6	
Input Setup and Hold Time Relative to Global Clock Input Signal for LVTTL Standard. For data input with different standards, adjust the setup time delay by the values shown in **IOB Input Switching Characteristics Standard Adjustments**, page 8.							
Full Delay	T_{PSFD}/T_{PHFD}	XCV50E	1.8 / 0	1.8 / 0	1.8 / 0	1.8 / 0	ns
Global Clock and IFF, without DLL		XCV100E	1.8 / 0	1.8 / 0	1.8 / 0	1.8 / 0	ns
		XCV200E	1.9 / 0	1.9 / 0	1.9 / 0	1.9 / 0	ns
		XCV300E	2.0 / 0	2.0 / 0	2.0 / 0	2.0 / 0	ns
		XCV400E	2.0 / 0	2.0 / 0	2.0 / 0	2.0 / 0	ns
		XCV600E	2.1 / 0	2.1 / 0	2.1 / 0	2.1 / 0	ns
		XCV1000E	2.3 / 0	2.3 / 0	2.3 / 0	2.3 / 0	ns
		XCV1600E	2.5 / 0	2.5 / 0	2.5 / 0	2.5 / 0	ns
		XCV2000E	2.5 / 0	2.5 / 0	2.5 / 0	2.5 / 0	ns
		XCV2600E	2.7 / 0	2.7 / 0	2.7 / 0	2.7 / 0	ns
		XCV3200E	2.8 / 0	2.8 / 0	2.8 / 0	2.8 / 0	ns

Notes:
1. IFF = Input Flip-Flop or Latch
2. Setup time is measured relative to the Global Clock input signal with the fastest route and the lightest load. Hold time is measured relative to the Global Clock input signal with the slowest route and heaviest load.
3. A Zero “0” Hold Time listing indicates no hold time or a negative hold time. Negative values can not be guaranteed “best-case”, but if a “0” is listed, there is no positive hold time.

Table 4: **CS144 — XCV50E, XCV100E, XCV200E**

Bank	Pin Description	Pin #
4	IO_L15N_YY	M11
4	IO_L15P_YY	L11
4	IO_L16N_YY	K9
4	IO_VREF_L16P_YY	N10[2]
4	IO_L17N_YY	K8
4	IO_L17P_YY	N9
4	IO_LVDS_DLL_L18P	N8
4	IO_VREF	L8
4	IO_VREF	L10
4	IO_VREF	N11[1]
5	GCK1	M7
5	IO	M4
5	IO_LVDS_DLL_L18N	M6
5	IO_L19N_YY	N5
5	IO_L19P_YY	K6
5	IO_VREF_L20N_YY	N4[2]
5	IO_L20P_YY	K5
5	IO_L21N_YY	M3
5	IO_L21P_YY	N3
5	IO_VREF	K4[1]
5	IO_VREF	L4
5	IO_VREF	L6
6	IO	G4
6	IO	J4
6	IO_L25P	H1
6	IO_VREF_L25N	H2
6	IO_L24P_YY	H3
6	IO_L24N_YY	H4
6	IO_L23P	J2
6	IO_VREF_L23N	J3[2]
6	IO_VREF	K1
6	IO_VREF	K2[1]
6	IO_L22N_YY	L1
6	IO_L22P_YY	K3

Table 4: **CS144 — XCV50E, XCV100E, XCV200E**

Bank	Pin Description	Pin #
6	IO_L26N	G1
7	IO	C2
7	IO	D3
7	IO	F3
7	IO_L26P	F2
7	IO_L27N	F4
7	IO_VREF_L27P	E1
7	IO_L28N_YY	E2
7	IO_L28P_YY	E3
7	IO_L29N	D1
7	IO_VREF_L29P	D2[2]
7	IO_VREF	C1[1]
7	IO_VREF	D4
2	CCLK	B13
3	DONE	M12
NA	M0	M1
NA	M1	L2
NA	M2	N2
NA	PROGRAM	L12
NA	TDI	A11
NA	TCK	C3
2	TDO	A12
NA	TMS	B1
NA	VCCINT	A9
NA	VCCINT	B6
NA	VCCINT	C5
NA	VCCINT	G3
NA	VCCINT	G12
NA	VCCINT	M5
NA	VCCINT	M9
NA	VCCINT	N6
0	VCCO	A2

Table 8: **HQ240 — XCV600E, XCV1000E**

Pin #	Pin Description	Bank
P210	GCK2	1
P209	IO_LVDS_DLL_L6P	1
P208	IO_VREF	1
P207	VCCO	1
P206	IO_L7N_Y	1
P205	IO_VREF_L7P_Y	1
P204	GND	NA
P203	IO_L8N_Y	1
P202	IO_L8P_Y	1
P201[1]	IO_VREF	1
P200	IO_L9N_YY	1
P199	IO_L9P_YY	1
P198	VCCINT	NA
P197	VCCO	1
P196	GND	NA
P195	IO_L10N_YY	1
P194	IO_VREF_L10P_YY	1
P193	IO_VREF	1
P192	IO_L11N_YY	1
P191	IO_VREF_L11P_YY	1
P190	GND	NA
P189	IO_L12N_YY	1
P188	IO_L12P_YY	1
P187	IO_VREF_L13N	1
P186	IO_L13P	1
P185	IO_WRITE_L14N_YY	1
P184	IO_CS_L14P_YY	1
P183	TDI	NA
P182	GND	NA
P181	TDO	2
P180	VCCO	1
P179	CCLK	2
P178	IO_DOUT_BUSY_L15P_YY	2
P177	IO_DIN_D0_L15N_YY	2
P176	VCCO	2
P175	IO_VREF	2

Table 8: **HQ240 — XCV600E, XCV1000E**

Pin #	Pin Description	Bank
P174	IO_L16P_Y	2
P173	IO_L16N_Y	2
P172	GND	NA
P171	IO_VREF_L17P_Y	2
P170	IO_L17N_Y	2
P169	IO_VREF	2
P168	IO_VREF_L18P_Y	2
P167	IO_D1_L18N_Y	2
P166	GND	NA
P165	VCCO	2
P164	VCCINT	NA
P163	IO_D2_L19P_YY	2
P162	IO_L19N_YY	2
P161[1]	IO_VREF	2
P160	IO_L20P_Y	2
P159	IO_L20N_Y	2
P158	GND	NA
P157	IO_VREF_L21P_Y	2
P156	IO_D3_L21N_Y	2
P155	IO_L22P_Y	2
P154	IO_VREF_L22N_Y	2
P153	IO_L23P_YY	2
P152	IO_L23N_YY	2
P151	GND	NA
P150	VCCO	2
P149	IO	3
P148	VCCINT	NA
P147	IO_VREF	3
P146	VCCO	3
P145	IO_D4_L24P_Y	3
P144	IO_VREF_L24N_Y	3
P143	GND	NA
P142	IO_L25P_Y	3
P141	IO_L25N_Y	3
P140[1]	IO_VREF	3
P139	IO_L26P_YY	3

Table 9: **HQ240 Differential Pin Pair Summary XCV600E, XCV1000E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
48	6	P56	P57	√	-
49	6	P52	P53	√	-
50	6	P49	P50	√	VREF
51	6	P46	P47	√	VREF
52	6	P41	P42	√	-
53	6	P38	P39	√	-
54	6	P35	P36	√	VREF
55	6	P33	P34	1	VREF
56	7	P27	P28	√	-
57	7	P23	P24	√	VREF
58	7	P20	P21	√	-
59	7	P17	P18	√	-
60	7	P12	P13	√	VREF
61	7	P9	P10	√	VREF
62	7	P6	P7	√	-
63	7	P4	P5	1	VREF

Note 1: AO in the XCV600E.

BG352 Ball Grid Array Packages

XCV100E, XCV200E, and XCV300E devices in BG352 Ball Grid Array packages have footprint compatibility. Pins labeled I0_VREF can be used as either in all parts unless device-dependent as indicated in the footnotes. If the pin is not used as V_{REF}, it can be used as general I/O. Immediately following Table 10, see Table 11 for Differential Pair information.

Table 10: **BG352 — XCV100E, XCV200E, XCV300E**

Bank	Pin Description	Pin #
0	IO	D22
0	IO	C23[1]
0	IO	B24[1]
0	IO	C22
0	IO_VREF_0_L0N_YY	D21[2]
0	IO_L0P_YY	B23
0	IO	A24[1]
0	IO_L1N_YY	A23
0	IO_L1P_YY	D20
0	IO_VREF_0_L2N_YY	C21
0	IO_L2P_YY	B22
0	IO	B21[1]
0	IO	C20[1]
0	IO_L3N	B20
0	IO_L3P	A21
0	IO	D18
0	IO_VREF_0_L4N_YY	C19
0	IO_L4P_YY	B19
0	IO_L5N_YY	D17
0	IO_L5P_YY	C18
0	IO	B18[1]
0	IO_L6N	C17
0	IO_L6P	A18
0	IO	D16[1]
0	IO_L7N_Y	B17
0	IO_L7P_Y	C16
0	IO_VREF_0_L8N_Y	A16
0	IO_L8P_Y	D15

Table 10: **BG352 — XCV100E, XCV200E, XCV300E**

Bank	Pin Description	Pin #
NA	VCCINT	V24
NA	VCCINT	R23
NA	VCCINT	P25
NA	VCCINT	L25
NA	VCCINT	J24
0	VCCO	D19
0	VCCO	B25
0	VCCO	A17
1	VCCO	D13
1	VCCO	D7
1	VCCO	A10
2	VCCO	K1
2	VCCO	H4
2	VCCO	B2
3	VCCO	Y4
3	VCCO	U1
3	VCCO	P4
4	VCCO	AF10
4	VCCO	AE2
4	VCCO	AC8
5	VCCO	AF17
5	VCCO	AC20
5	VCCO	AC14
6	VCCO	AE25
6	VCCO	W23
6	VCCO	U26
7	VCCO	N23
7	VCCO	K26
7	VCCO	G23
NA	GND	A26
NA	GND	A25
NA	GND	A22

Table 10: **BG352 — XCV100E, XCV200E, XCV300E**

Bank	Pin Description	Pin #
NA	GND	A19
NA	GND	A14
NA	GND	A8
NA	GND	A5
NA	GND	A2
NA	GND	A1
NA	GND	B26
NA	GND	B1
NA	GND	E26
NA	GND	E1
NA	GND	H26
NA	GND	H1
NA	GND	N1
NA	GND	P26
NA	GND	W26
NA	GND	W1
NA	GND	AB26
NA	GND	AB1
NA	GND	AE26
NA	GND	AE1
NA	GND	AF26
NA	GND	AF25
NA	GND	AF22
NA	GND	AF19
NA	GND	AF13
NA	GND	AF8
NA	GND	AF5
NA	GND	AF2
NA	GND	AF1

Notes:
1. No Connect in the XCV100E.
2. V_{REF} or I/O option only in the XCV200E and XCV300E; otherwise, I/O option only.

Table 11: **BG352 Differential Pin Pair Summary XCV100E, XCV200E, XCV300E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
55	5	AC13	AD14	√	GCLK LVDS 1/0
56	5	AD15	AC15	√	VREF_5
57	5	AE16	AE17	√	-
58	5	AC16	AF18	2	-
59	5	AD17	AC17	√	-
60	5	AD18	AC18	√	VREF_5
61	5	AF20	AE20	1	-
62	5	AE21	AD20	√	VREF_5
63	5	AF23	AE22	√	-
64	5	AC21	AE23	√	VREF_5
65	6	AD25	AC24	√	-
66	6	AC26	AD26	√	VREF_6
67	6	AB25	AA24	√	-
68	6	Y24	AA25	√	VREF_6
69	6	W24	V23	2	-
70	6	U23	Y26	√	VREF_6
71	6	U24	V25	√	-
72	6	U25	T23	1	-
73	6	T26	T25	√	-
74	6	R25	R24	√	VREF_6
75	6	P24	R26	2	-
76	7	N24	N25	√	-
77	7	M24	M25	2	-
78	7	L26	M23	√	VREF_7
79	7	L24	K25	√	-
80	7	J25	J26	1	-
81	7	H25	K23	√	-
82	7	G26	J23	√	VREF_7
83	7	H24	G25	1	-
84	7	D26	G24	√	VREF_7
85	7	F24	E25	√	-
86	7	E24	D25	√	VREF_7

Notes:
1. AO in the XCV100E.
2. AO in the XCV200E.

BG432 Ball Grid Array Packages

XCV300E, XCV400E, and XCV600E devices in BG432 Ball Grid Array packages have footprint compatibility. Pins labeled I0_VREF can be used as either in all parts unless device-dependent as indicated in the footnotes. If the pin is not used as V_{REF}, it can be used as general I/O. Immediately following Table 12, see Table 13 for Differential Pair information.

Table 12: **BG432 — XCV300E, XCV400E, XCV600E**

Bank	Pin Description	Pin #
0	GCK3	D17
0	IO	A22
0	IO	A26
0	IO	B20
0	IO	C23
0	IO	C28
0	IO_L0N_Y	B29
0	IO_L0P_Y	D27
0	IO_L1N_YY	B28
0	IO_L1P_YY	C27
0	IO_VREF_L2N_YY	D26
0	IO_L2P_YY	A28
0	IO_L3N_Y	B27
0	IO_L3P_Y	C26
0	IO_L4N_YY	D25
0	IO_L4P_YY	A27
0	IO_VREF_L5N_YY	D24
0	IO_L5P_YY	C25
0	IO_L6N_Y	B25
0	IO_L6P_Y	D23
0	IO_VREF_L7N_Y	C24[1]
0	IO_L7P_Y	B24
0	IO_VREF_L8N_YY	D22
0	IO_L8P_YY	A24
0	IO_L9N_YY	C22
0	IO_L9P_YY	B22
0	IO_L10N_YY	C21
0	IO_L10P_YY	D20
0	IO_L11N_YY	B21
0	IO_L11P_YY	C20

Table 13: **BG432 Differential Pin Pair Summary XCV300E, XCV400E, XC600E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
112	6	AB29	AB28	√	VREF
113	6	AA29	AB31	√	-
114	6	Y29	Y28	4	-
115	6	Y31	Y30	1	-
116	6	W30	W29	1	-
117	6	V29	V28	√	VREF
118	6	U29	V30	4	-
119	6	U30	U28	1	VREF
120	7	R29	T31	√	-
121	7	R31	R30	1	VREF
122	7	P28	P29	4	-
123	7	N30	P30	√	VREF
124	7	N31	N28	1	-
125	7	M28	M29	1	-
126	7	L30	M30	4	-
127	7	K30	K31	√	-
128	7	J30	K28	√	VREF
129	7	J28	J29	1	VREF
130	7	G30	H30	4	-
131	7	F31	H28	√	VREF
132	7	G28	G29	1	-
133	7	E30	E31	5	-
134	7	F28	F29	1	VREF
135	7	D30	D31	4	-
136	7	E28	E29	3	-

Notes:
1. AO in the XCV300E, 600E.
2. AO in the XCV300E.
3. AO in the XCV400E, 600E.
4. AO in the XCV300E, 400E.
5. AO in the XCV600E.

BG560 Ball Grid Array Packages

XCV1000E, XCV1600E, and XCV2000E devices in BG560 Ball Grid Array packages have footprint compatibility. Pins labeled I0_VREF can be used as either in all parts unless device-dependent as indicated in the footnotes. If the pin is not used as V_{REF}, it can be used as general I/O. Immediately following Table 14, see Table 15 for Differential Pair information.

Table 14: **BG560 — XCV400E, XCV600E, XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin#	See Note
0	GCK3	A17	
0	IO	A27	
0	IO	B25	
0	IO	C28	
0	IO	C30	
0	IO	D30	
0	IO_L0N	E28	
0	IO_VREF_L0P	D29	3
0	IO_L1N_YY	D28	
0	IO_L1P_YY	A31	
0	IO_VREF_L2N_YY	E27	
0	IO_L2P_YY	C29	
0	IO_L3N_Y	B30	
0	IO_L3P_Y	D27	
0	IO_L4N_YY	E26	
0	IO_L4P_YY	B29	
0	IO_VREF_L5N_YY	D26	
0	IO_L5P_YY	C27	
0	IO_L6N_Y	E25	
0	IO_VREF_L6P_Y	A28	1
0	IO_L7N_Y	D25	
0	IO_L7P_Y	C26	
0	IO_VREF_L8N_Y	E24	4
0	IO_L8P_Y	B26	
0	IO_L9N_Y	C25	
0	IO_L9P_Y	D24	
0	IO_VREF_L10N_YY	E23	
0	IO_L10P_YY	A25	
0	IO_L11N_YY	D23	

BG560 Differential Pin Pairs

Virtex-E devices have differential pin pairs that can also provide other functions when not used as a differential pair. A √ in the AO column indicates that the pin pair can be used as an asynchronous output for all devices provided in this package. Pairs with a note number in the AO column are device dependent. They can have asynchronous outputs if the pin pair are in the same CLB row and column in the device. Numbers in this column refer to footnotes that indicate which devices have pin pairs than can be asynchronous outputs. The Other Functions column indicates alternative function(s) not available when the pair is used as a differential pair or differential clock.

Table 15: **BG560 Differential Pin Pair Summary**
XCV400E, XCV600E, XCV1000E, XCV1600E, XCV2000E

Pair	Bank	P Pin	N Pin	AO	Other Functions
Global Differential Clock					
0	4	AL17	AM17	NA	IO_DLL_L15P
1	5	AJ17	AM18	NA	IO_DLL_L15N
2	1	D17	E17	NA	IO_DLL_L21P
3	0	A17	C18	NA	IO_DLL_L21N
IO LVDS Total Outputs: 183, Asynchronous Outputs: 87					
0	0	D29	E28	8	VREF
1	0	A31	D28	√	-
2	0	C29	E27	√	VREF
3	0	D27	B30	3	-
4	0	B29	E26	√	-
5	0	C27	D26	√	VREF
6	0	A28	E25	9	VREF
7	0	C26	D25	7	-
8	0	B26	E24	7	VREF
9	0	D24	C25	2	-
10	0	A25	E23	√	VREF
11	0	B24	D23	√	-
12	0	C23	E22	8	-
13	0	D22	A23	√	-
14	0	B22	E21	√	VREF
15	0	C21	D21	3	-

Table 15: **BG560 Differential Pin Pair Summary**
XCV400E, XCV600E, XCV1000E, XCV1600E, XCV2000E

Pair	Bank	P Pin	N Pin	AO	Other Functions
16	0	E20	B21	√	-
17	0	C20	D20	√	VREF
18	0	E19	B20	9	-
19	0	C19	D19	7	-
20	0	D18	A19	7	VREF
21	1	E17	C18	NA	IO_LVDS_DLL
22	1	B17	C17	2	VREF
23	1	D16	B16	7	VREF
24	1	C16	E16	7	-
25	1	C15	A15	9	-
26	1	E15	D15	√	VREF
27	1	D14	C14	√	-
28	1	E14	A13	3	-
29	1	D13	C13	√	VREF
30	1	E13	C12	√	-
31	1	D12	A11	8	-
32	1	C11	B11	√	-
33	1	D11	B10	√	VREF
34	1	A9	C10	10	-
35	1	D10	C9	7	VREF
36	1	B8	A8	7	-
37	1	C8	E10	5	VREF
38	1	A6	B7	√	VREF
39	1	D8	C7	√	-
40	1	B5	A5	11	-
41	1	D7	C6	√	VREF
42	1	B4	A4	√	-
43	1	E7	C5	12	VREF
44	1	A2	D6	√	CS
45	2	D4	E4	√	DIN, D0
46	2	F5	B3	17	VREF

Table 19: **FG456 Differential Pin Pair Summary XCV200E, XCV300E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
18	1	C14	B14	2	-
19	1	A15	F12	2	-
20	1	C15	B15	√	-
21	1	E14	A16	√	VREF
22	1	C16	D14	2	-
23	1	A17	D15	2	-
24	1	A18	B17	√	VREF
25	1	C17	D16	√	-
26	1	A19	B18	√	VREF
27	1	C18	D17	√	-
28	1	C19	A20	√	CS
29	2	C21	D20	√	DIN, D0
30	2	C22	D21	√	-
31	2	D22	E21	√	VREF
32	2	E22	F18	√	-
33	2	F21	F19	√	VREF
34	2	F22	G19	2	-
35	2	G20	G18	1	-
36	2	H18	H22	2	D1, VREF
37	2	H20	H19	√	D2
38	2	H21	J19	√	-
39	2	J18	J20	√	-
40	2	K18	J21	2	-
41	2	K22	K21	1	VREF
42	2	K19	L22	2	-
43	2	L21	L18	√	-
44	2	L17	L20	√	-
45	3	M18	M20	√	-
46	3	M19	M17	2	-
47	3	N22	N21	2	VREF
48	3	N20	N18	√	-
49	3	N19	P21	√	-
50	3	P20	P19	√	-
51	3	P18	R21	√	D5
52	3	T22	R19	2	VREF

Table 19: **FG456 Differential Pin Pair Summary XCV200E, XCV300E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
53	3	U22	R18	2	-
54	3	T21	V22	√	-
55	3	T20	U21	√	VREF
56	3	W22	T18	√	-
57	3	U19	U20	√	VREF
58	3	W21	AA22	√	-
59	3	Y21	V19	√	INIT
60	4	W18	AA20	√	-
61	4	Y18	V17	NA	-
62	4	AB20	W17	√	VREF
63	4	AA18	V16	NA	-
64	4	AB19	AB18	√	VREF
65	4	W16	AA17	1	-
66	4	Y16	V15	1	-
67	4	AB16	Y15	√	VREF
68	4	AA15	AB15	√	-
69	4	W15	Y14	1	-
70	4	V14	AA14	1	-
71	4	AB14	V13	NA	-
72	4	AA13	AB13	√	VREF
73	4	W13	AA12	2	-
74	4	Y12	V12	2	-
75	5	U12	AA11	NA	IO_LVDS_DLL
76	5	AB11	W11	1	-
77	5	V11	Y10	√	VREF
78	5	AB10	W10	√	-
79	5	V10	Y9	2	-
80	5	AB9	W9	2	-
81	5	V9	AA8	√	-
82	5	Y8	W8	√	VREF
83	5	W7	AA7	2	-
84	5	AB6	AA6	2	-
85	5	AB5	AA5	√	VREF
86	5	Y7	W6	√	-
87	5	AA4	Y6	√	VREF

Table 22: **FG680 - XCV600E, XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin #
5	IO_L166P_YY	AV26
5	IO_L166N_YY	AW27
5	IO_L167P_Y	AU26
5	IO_L167N_Y	AV27
5	IO_L168P_Y	AT26
5	IO_L168N_Y	AW28
5	IO_L169P_YY	AU27
5	IO_L169N_YY	AV28
5	IO_L170P_YY	AW29
5	IO_VREF_L170N_YY	AT27
5	IO_L171P_Y	AW30
5	IO_L171N_Y	AU28
5	IO_L172P_Y	AV30
5	IO_L172N_Y	AV29
5	IO_L173P_YY	AW31
5	IO_VREF_L173N_YY	AU29
5	IO_L174P_YY	AV31
5	IO_L174N_YY	AT29
5	IO_L175P_Y	AW32
5	IO_VREF_L175N_Y	AU30[3]
5	IO_L176P_Y	AW33
5	IO_L176N_Y	AT30
5	IO_L177P_YY	AV33
5	IO_VREF_L177N_YY	AU31
5	IO_L178P_YY	AT31
5	IO_L178N_YY	AW34
5	IO_L179P_Y	AV32
5	IO_L179N_Y	AV34
5	IO_L180P_Y	AU32
5	IO_L180N_Y	AW35
5	IO_L181P_YY	AT32
5	IO_VREF_L181N_YY	AV35
5	IO_L182P_YY	AU33
5	IO_L182N_YY	AW36
5	IO_L183P_Y	AT33
5	IO_VREF_L183N_Y	AV36[1]

Table 22: **FG680 - XCV600E, XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin #
5	IO_L184P_Y	AU34
5	IO_L184N_Y	AU36
6	IO	W39
6	IO	AR37
6	IO	AR39
6	IO_L185N_YY	AR36
6	IO_L185P_YY	AT38
6	IO_L186N_Y	AR38
6	IO_L186P_Y	AP36
6	IO_VREF_L187N	AT39[1]
6	IO_L187P	AP37
6	IO_L188N	AP38
6	IO_L188P	AP39
6	IO_VREF_L189N_Y	AN36
6	IO_L189P_Y	AN38
6	IO_L190N_YY	AN37
6	IO_L190P_YY	AN39
6	IO_L191N	AM36
6	IO_L191P	AM38
6	IO_L192N_Y	AM37
6	IO_L192P_Y	AL36
6	IO_VREF_L193N_YY	AM39
6	IO_L193P_YY	AL37
6	IO_L194N_YY	AL38
6	IO_L194P_YY	AK36
6	IO_VREF_L195N	AL39[3]
6	IO_L195P	AK37
6	IO_L196N	AK38
6	IO_L196P	AJ36
6	IO_VREF_L197N_YY	AK39
6	IO_L197P_YY	AJ37
6	IO_L198N_YY	AJ38
6	IO_L198P_YY	AH37
6	IO_L199N	AJ39
6	IO_L199P	AH38

Table 22: **FG680 - XCV600E, XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin #
6	IO_VREF_L200N_YY	AH39
6	IO_L200P_YY	AG38
6	IO_L201N_YY	AG36
6	IO_L201P_YY	AG39
6	IO_L202N_Y	AG37
6	IO_L202P_Y	AF39
6	IO_L203N	AF36
6	IO_L203P	AE38
6	IO_L204N	AF37
6	IO_L204P	AF38
6	IO_VREF_L205N_Y	AE39[1]
6	IO_L205P_Y	AE36
6	IO_L206N_YY	AD38
6	IO_L206P_YY	AE37
6	IO_L207N	AD39
6	IO_L207P	AD36
6	IO_L208N_Y	AC38
6	IO_L208P_Y	AC39
6	IO_VREF_L209N_YY	AD37
6	IO_L209P_YY	AB38
6	IO_L210N_YY	AC35
6	IO_L210P_YY	AB39
6	IO_L211N	AC36
6	IO_L211P	AA38
6	IO_L212N	AC37
6	IO_L212P	AA39
6	IO_VREF_L213N_YY	AB35
6	IO_L213P_YY	Y38
6	IO_L214N_YY	AB36
6	IO_L214P_YY	Y39
6	IO_VREF_L215N	AB37[2]
6	IO_L215P	AA36
7	IO	C38
7	IO	B37
7	IO	F37

Table 22: **FG680 - XCV600E, XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin #
7	IO_L216N_YY	AA37
7	IO_L216P_YY	W38
7	IO_L217N	W37
7	IO_VREF_L217P	V39[2]
7	IO_L218N_YY	W36
7	IO_L218P_YY	U39
7	IO_L219N_YY	V38
7	IO_VREF_L219P_YY	U38
7	IO_L220N	V37
7	IO_L220P	T39
7	IO_L221N	V36
7	IO_L221P	T38
7	IO_L222N_YY	V35
7	IO_L222P_YY	R39
7	IO_L223N_YY	U37
7	IO_VREF_L223P_YY	U36
7	IO_L224N_Y	R38
7	IO_L224P_Y	U35
7	IO_L225N	P39
7	IO_L225P	T37
7	IO_L226N_YY	P38
7	IO_L226P_YY	T36
7	IO_L227N_Y	N39
7	IO_VREF_L227P_Y	N38[1]
7	IO_L228N	R37
7	IO_L228P	M39
7	IO_L229N	R36
7	IO_L229P	M38
7	IO_L230N_Y	P37
7	IO_L230P_Y	L39
7	IO_L231N_YY	P36
7	IO_L231P_YY	N37
7	IO_L232N_YY	L38
7	IO_VREF_L232P_YY	N36
7	IO_L233N	K39
7	IO_L233P	M37

Table 26: **FG900 — XCV600E, XCV1000E, XCV1600E**

Bank	Pin Description	Pin #
0	IO_L6N_Y	A5
0	IO_L6P_Y	F8
0	IO_L7N_Y	D7
0	IO_L7P_Y	N11
0	IO_L8N_YY	G9
0	IO_L8P_YY	E8
0	IO_VREF_L9N_YY	A6
0	IO_L9P_YY	J11
0	IO_L10N_Y	C7
0	IO_L10P_Y	B7
0	IO_L11N_Y	C8
0	IO_L11P_Y	H10
0	IO_L12N_YY	G10
0	IO_L12P_YY	F10
0	IO_VREF_L13N_YY	A8
0	IO_L13P_YY	H11
0	IO_L14N	D9[4]
0	IO_L14P	C9[3]
0	IO_L15N_YY	B9
0	IO_L15P_YY	J12
0	IO_L16N	E10[4]
0	IO_VREF_L16P	A9
0	IO_L17N	G11
0	IO_L17P	B10
0	IO_L18N_YY	H12[4]
0	IO_L18P_YY	C10[4]
0	IO_L19N_Y	H13
0	IO_L19P_Y	F11
0	IO_L20N_Y	E11
0	IO_L20P_Y	D11
0	IO_L21N_Y	B11[4]
0	IO_L21P_Y	G12[4]
0	IO_L22N_YY	F12
0	IO_L22P_YY	C11
0	IO_VREF_L23N_YY	A10[1]
0	IO_L23P_YY	D12
0	IO_L24N_Y	E12

Table 26: **FG900 — XCV600E, XCV1000E, XCV1600E**

Bank	Pin Description	Pin #
0	IO_L24P_Y	A11
0	IO_L25N_Y	G13
0	IO_L25P_Y	B12
0	IO_L26N_YY	A12
0	IO_L26P_YY	K13
0	IO_VREF_L27N_YY	F13
0	IO_L27P_YY	B13
0	IO_L28N_Y	G14
0	IO_L28P_Y	E13
0	IO_L29N_Y	D14
0	IO_L29P_Y	B14
0	IO_L30N_YY	A14
0	IO_L30P_YY	J14
0	IO_VREF_L31N_YY	K14
0	IO_L31P_YY	J15
0	IO_L32N	B15[4]
0	IO_L32P	H15[3]
0	IO_VREF_L33N_YY	F15[2,3]
0	IO_L33P_YY	D15[4]
0	IO_LVDS_DLL_L34N	A15
1	GCK2	E15
1	IO	A25[4]
1	IO	B17[4]
1	IO	B18[4]
1	IO	C23[4]
1	IO	D16[4]
1	IO	D17[5]
1	IO	D23[4]
1	IO	E19[4]
1	IO	E24[5]
1	IO	F22[4]
1	IO	G17[5]
1	IO	G20[4]
1	IO	J16[4]
1	IO	J17[4]
1	IO	J19[5]

Table 26: **FG900 — XCV600E, XCV1000E, XCV1600E**

Bank	Pin Description	Pin #
NA	GND	AG27
NA	GND	D27
NA	GND	AF26
NA	GND	E26
NA	GND	F25
NA	GND	AE25
NA	GND	G24
NA	GND	AJ23
NA	GND	AD24
NA	GND	H23
NA	GND	B23
NA	GND	AC23
NA	GND	AB22
NA	GND	V22
NA	GND	N22
NA	GND	AH18
NA	GND	AB18
NA	GND	J18
NA	GND	C18
NA	GND	U17
NA	GND	T17
NA	GND	R17
NA	GND	P17
NA	GND	U16
NA	GND	T16
NA	GND	R16
NA	GND	P16
NA	GND	U15
NA	GND	T15
NA	GND	R15
NA	GND	P15
NA	GND	U14
NA	GND	T14
NA	GND	R14
NA	GND	P14
NA	GND	AH13
NA	GND	AB13

Table 26: **FG900 — XCV600E, XCV1000E, XCV1600E**

Bank	Pin Description	Pin #
NA	GND	J13
NA	GND	C13
NA	GND	V9
NA	GND	N9
NA	GND	J9
NA	GND	AJ8
NA	GND	AC8
NA	GND	H8
NA	GND	AD7
NA	GND	B8
NA	GND	AE6
NA	GND	G7
NA	GND	F6
NA	GND	AF5
NA	GND	E5
NA	GND	AG4
NA	GND	D4
NA	GND	V3
NA	GND	N3
NA	GND	C3
NA	GND	AK2
NA	GND	AH3
NA	GND	AC2
NA	GND	H2
NA	GND	B2
NA	GND	A2
NA	GND	AK1
NA	GND	AJ2
NA	GND	AJ1
NA	GND	A1
NA	GND	B1

Notes:

1. V_{REF} or I/O option only in the XCV1000E and XCV1600E; otherwise, I/O option only.
2. V_{REF} or I/O option only in the XCV1600E; otherwise, I/O option only.
3. I/O option only in the XCV600E.
4. No Connect in the XCV600E.
5. No Connect in the XCV600E, 1000E.

Table 27: **FG900 Differential Pin Pair Summary XCV600E, XCV1000E, XCV1600E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
188	5	AA12	AJ12	√	VREF
189	5	AB12	AE11	√	-
190	5	AK12	Y13	2	-
191	5	AG11	AF11	2	-
192	5	AH11	AJ11	2	-
193	5	AE12	AG10	4	-
194	5	AD12	AK11	√	-
195	5	AJ10	AC12	√	VREF
196	5	AK10	AD11	4	-
197	5	AJ9	AE9	4	-
198	5	AH10	AF9	√	VREF
199	5	AH9	AK9	√	-
200	5	AF8	AB11	2	-
201	5	AC11	AG8	2	-
202	5	AK8	AF7	√	VREF
203	5	AG7	AK7	√	-
204	5	AJ7	AD10	1	-
205	5	AH6	AC10	1	-
206	5	AD9	AG6	√	VREF
207	5	AB10	AJ5	√	-
208	5	AD8	AK5	2	-
209	5	AC9	AJ4	2	VREF
210	5	AG5	AK4	2	-
211	5	AH5	AG3	4	-
212	6	AC6	AF3	√	-
213	6	AG2	AH2	NA	-
214	6	AE4	AB9	1	-
215	6	AH1	AE3	4	VREF
216	6	AD6	AB8	3	-
217	6	AA10	AG1	4	-
218	6	AD4	AA9	1	VREF
219	6	AD2	AD5	√	-
220	6	AF2	AD3	4	-
221	6	AA7	AA8	1	-

Table 27: **FG900 Differential Pin Pair Summary XCV600E, XCV1000E, XCV1600E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
222	6	Y9	AF1	√	VREF
223	6	AC4	AB6	√	-
224	6	W8	AE1	2	-
225	6	AB4	Y8	4	-
226	6	W9	AB3	4	VREF
227	6	W10	AA5	4	-
228	6	V10	AB1	4	-
229	6	AC1	Y7	4	VREF
230	6	AA3	V11	NA	-
231	6	U10	AA2	4	-
232	6	AA6	W7	1	-
233	6	Y4	Y6	4	-
234	6	V7	AA1	3	-
235	6	Y2	Y3	4	-
236	6	W5	Y5	1	VREF
237	6	W6	W4	√	-
238	6	W2	V6	4	-
239	6	V4	U9	1	-
240	6	T8	AB2	√	VREF
241	6	W1	U5	√	-
242	6	T9	Y1	2	-
243	6	U3	T7	4	-
244	6	V2	T5	4	VREF
245	6	T6	R9	4	-
246	6	U2	T4	4	VREF
247	7	R10	T1	NA	
248	7	R6	R5	4	-
249	7	R4	R8	4	VREF
250	7	R3	R7	4	-
251	7	P6	P10	4	VREF
252	7	P2	P5	4	-
253	7	P4	P7	2	-
254	7	R2	N4	√	-
255	7	P1	N7	√	VREF

Table 28: **FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Bank	Pin Description	Pin #
4	IO_L178N_YY	AL28
4	IO_L179P_YY	AE24[4]
4	IO_L179N_YY	AN28[5]
4	IO_L180P_Y	AJ27
4	IO_L180N_Y	AH26
4	IO_L181P_Y	AG25
4	IO_L181N_Y	AK27
4	IO_L182P	AM28[4]
4	IO_L182N	AF24[5]
4	IO_L183P_YY	AJ26
4	IO_L183N_YY	AP27
4	IO_VREF_L184P_YY	AK26
4	IO_L184N_YY	AN27
4	IO_L185P	AE23[4]
4	IO_L185N	AM27[5]
4	IO_L186P_Y	AL26
4	IO_L186N_Y	AP26
4	IO_VREF_L187P_Y	AN26[2]
4	IO_L187N_Y	AJ25
4	IO_L188P	AG24[4]
4	IO_L188N	AP25[5]
4	IO_L189P_YY	AF23
4	IO_L189N_YY	AM26
4	IO_VREF_L190P_YY	AJ24
4	IO_L190N_YY	AN25
4	IO_L191P_Y	AE22
4	IO_L191N_Y	AM25
4	IO_L192P_Y	AK24
4	IO_L192N_Y	AH23
4	IO_VREF_L193P_YY	AF22
4	IO_L193N_YY	AP24
4	IO_L194P_YY	AL24
4	IO_L194N_YY	AK23
4	IO_L195P_Y	AG22

Table 28: **FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Bank	Pin Description	Pin #
4	IO_L195N_Y	AN23
4	IO_L196P_Y	AP23
4	IO_L196N_Y	AM23
4	IO_L197P_Y	AH22
4	IO_L197N_Y	AP22
4	IO_L198P_Y	AL23
4	IO_L198N_Y	AF21
4	IO_L199P_YY	AL22
4	IO_L199N_YY	AJ22
4	IO_VREF_L200P_YY	AK22
4	IO_L200N_YY	AM22
4	IO_L201P_YY	AG21[4]
4	IO_L201N_YY	AJ21[5]
4	IO_L202P_Y	AP21
4	IO_L202N_Y	AE20
4	IO_L203P_Y	AH21
4	IO_L203N_Y	AL21
4	IO_L204P	AN21[4]
4	IO_L204N	AF20[5]
4	IO_L205P_YY	AK21
4	IO_L205N_YY	AP20
4	IO_VREF_L206P_YY	AE19
4	IO_L206N_YY	AN20
4	IO_L207P_Y	AG20[4]
4	IO_L207N_Y	AL20[5]
4	IO_L208P_Y	AH20
4	IO_L208N_Y	AK20
4	IO_L209P_Y	AN19
4	IO_L209N_Y	AJ20
4	IO_L210P	AF19[4]
4	IO_L210N	AP19[5]
4	IO_L211P_YY	AM19
4	IO_L211N_YY	AH19
4	IO_VREF_L212P_YY	AJ19